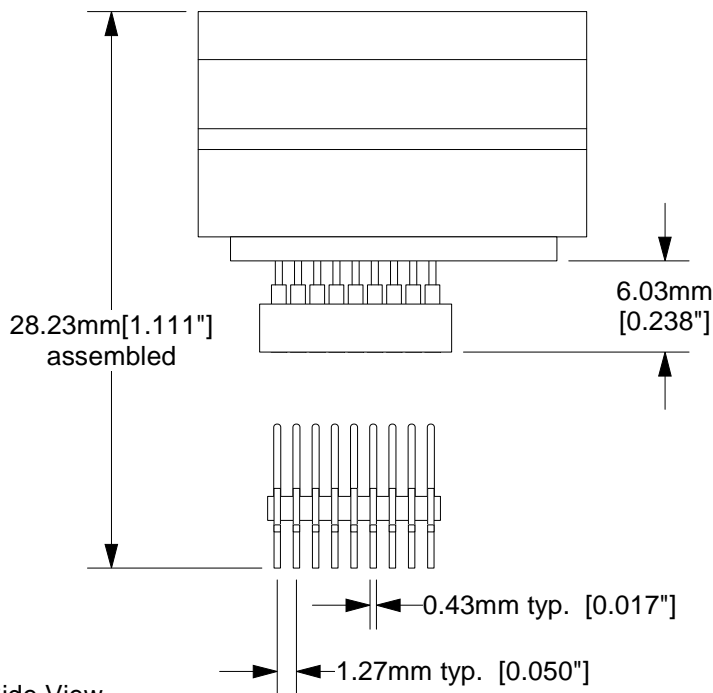
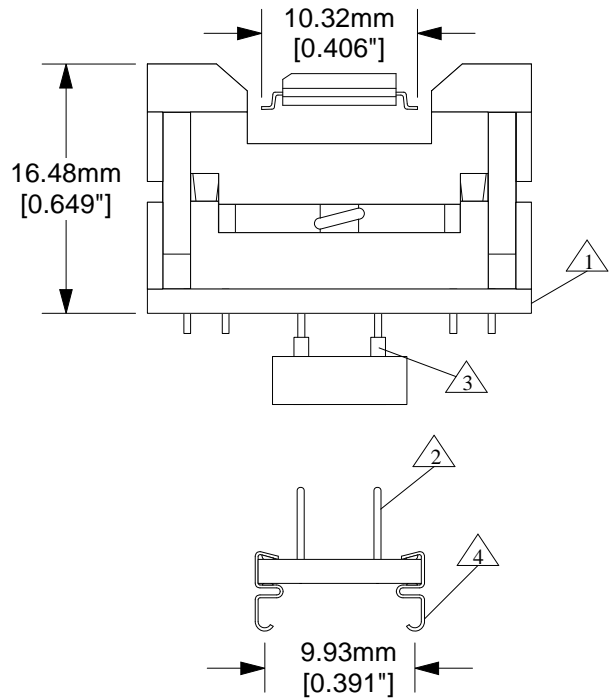


Top View



Side View



End View

1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"] FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. SnPb plating.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ "] Au over 1.27 $\mu$ m [50 $\mu$ "] Ni (min.).


3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ "] Au over 1.27 $\mu$ m [50 $\mu$ "] Ni (min.). Contact material- BeCu; finish 0.25 $\mu$ m [10 $\mu$ "] Au over 2.54 $\mu$ m [100 $\mu$ "] Ni (min. ).

4 Leads: material- BeCu Alloy 194; plating- 60/40 SnPb 3.80-10.16 $\mu$ m [150-400 $\mu$ "].

Description: **CARRIER ADAPTOR**

18 position SOIC ZIF Socket to 18 position SOIC J-leaded Surface Mountable Emulator foot. Pin assignment is 1:1.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise.

	<b>CA-SO18A-Z-J-01 Drawing</b>	Status: Released	Scale: 2:1	Rev: C
	© 1996 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing by: E. Swanson		Date: 5/16/96
		File: CA-SO18A-Z-J-01 Dwg	Modified: 5/12/00	